## 捷多邦,专业PCB打样工厂,24小时加**含N74**AHC00-Q1 QUADRUPLE 2-INPUT POSITIVE-NAND GATE

SGDS013A - FEBRUARY 2002 - REVISED NOVEMBER 2004

- Qualification in Accordance With AEC-Q100†
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Operating Range 2-V to 5.5-V V<sub>CC</sub>
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

#### D OR PW PACKAGE (TOP VIEW)

_			1
1	$\cup$	14	Vcc
		13	4B
3		12	] 4A
4		11	] 4Y
5		10	] 3B
6		9	] 3A
7		8	3Y
	4 5 6	3 4 5 6	2 13 3 12 4 11 5 10 6 9

## description/ordering information

The SN74AHC00 device performs the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

#### ORDERING INFORMATION

T <sub>A</sub>	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Tape and reel	SN74AHC00QDRQ1	AHC00Q
-40°C to 125°C	TSSOP - PW	Tape and reel	SN74AHC00QPWRQ1	HA00Q
-40°C to 85°C	SOIC - D	Tape and reel	SN74AHC00IDRQ1	AHC00I
-40°C 10 85°C	TSSOP - PW	Tape and reel	SN74AHC00IPWRQ1	HA00I

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## FUNCTION TABLE (each gate)

INPU	JTS	OUTPUT
Α	В	Y
Н	Н	L
L	Χ	Н
X	L	Н

logic diagram, each gate (positive logic)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>†</sup>Contact factory for details. Q100 qualification data available on request.

## SN74AHC00-Q1 QUADRUPLE 2-INPUT POSITIVE-NAND GATE

SGDS013A - FEBRUARY 2002 - REVISED NOVEMBER 2004

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$-0.5$ V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	V to $V_{CC}$ + 0.5 V
Input clamp current, $I_{ K }(V_{ I } < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	
Continuous current through V <sub>CC</sub> or GND	
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	86°C/W
(see Note 2): PW package	
Storage temperature range, T <sub>stq</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
ViH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		
		V <sub>CC</sub> = 2 V		0.5	
٧ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65	
٧ı	Input voltage	•	0	5.5	V
٧o	Output voltage		0	VCC	V
		V <sub>CC</sub> = 2 V		-50	μΑ
lOH	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	
		$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V <sub>CC</sub> = 2 V		50	μΑ
lOL	Low-level output current	V <sub>CC</sub> = 3.3 V ± 0.3 V		4	
		$V_{CC} = 5 V \pm 0.5 V$		8	mA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	100		
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		20	ns/V
_		Q-suffix devices	-40	125	00
TA	Operating free-air temperature	I-suffix devices	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## SN74AHC00-Q1 QUADRUPLE 2-INPUT POSITIVE-NAND GATE

SGDS013A - FEBRUARY 2002 - REVISED NOVEMBER 2004

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to 125°C		T <sub>A</sub> = -40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
		2 V	1.9	2		1.9		1.9		
	I <sub>OH</sub> = -50 μA	3 V	2.9	3		2.9		2.9		
VOH		4.5 V	4.4	4.5		4.4		4.4		V
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		3.8		
		2 V			0.1		0.1		0.1	
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1		0.1	
VOL		4.5 V			0.1		0.1		0.1	V
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.5		0.44	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.5		0.44	
II	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20		20	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		2	10				10	pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO LOAD		T,	4 = 25°C	;	T <sub>A</sub> = -4		T <sub>A</sub> = -4		UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
tPLH	A on B	V	0. 45.5		5.5	7.9	1	9.5	1	9.5	
<sup>t</sup> PHL	A or B	Ť	C <sub>L</sub> = 15 pF		5.5	7.9	1	9.5	1	9.5	ns
<sup>t</sup> PLH	A or B	~	C: - 50 pE		8	11.4	1	13	1	13	nc
tPHL	AUID	· '	$C_L = 50 pF$		8	11.4	1	13	1	13	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T	դ = 25°C	;	T <sub>A</sub> = -4 125		T <sub>A</sub> = -4		UNIT
	(INPUT)	(001701)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A B	V	0 455		3.7	5.5	1	6.5	1	6.5	
<sup>t</sup> PHL	A or B	Y	C <sub>L</sub> = 15 pF		3.7	5.5	1	6.5	1	6.5	ns
tPLH .	A or B	V	C: - 50 pF		5.2	7.5	1	8.5	1	8.5	20
<sup>t</sup> PHL	AUB	ľ	C <sub>L</sub> = 50 pF		5.2	7.5	1	8.5	1	8.5	ns

## noise characteristics, $V_{CC} = 5 \text{ V}$ , $C_L = 50 \text{ pF}$ , $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic VOL		0.3	0.8	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.3	-0.8	V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>		4.6		V
V <sub>IH(D)</sub>	High-level dynamic input voltage	3.5			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			1.5	V

NOTE 4: Characteristics are for surface-mount packages only.



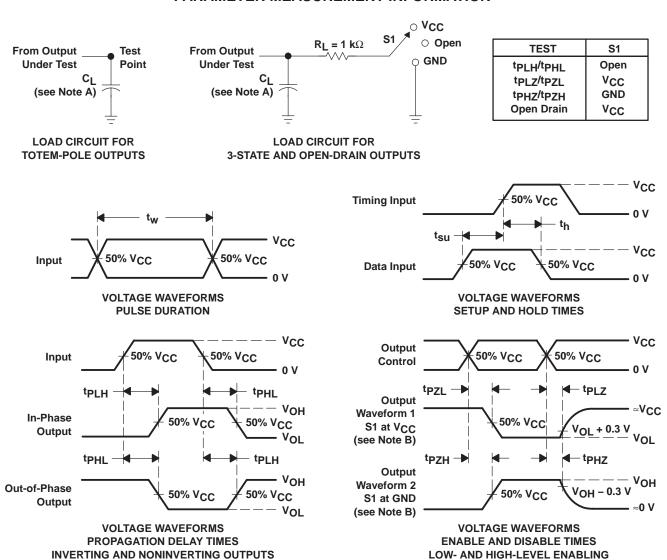
## SN74AHC00-Q1 QUADRUPLE 2-INPUT POSITIVE-NAND GATE

SGDS013A - FEBRUARY 2002 - REVISED NOVEMBER 2004

#### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	9.5	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z  $_{\mbox{O}}$  = 50  $\Omega,\,t_{\mbox{f}}\leq$  3 ns,  $t_{\mbox{f}}\leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





#### PACKAGE OPTION ADDENDUM

24-Jan-2006

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC00QDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC00QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

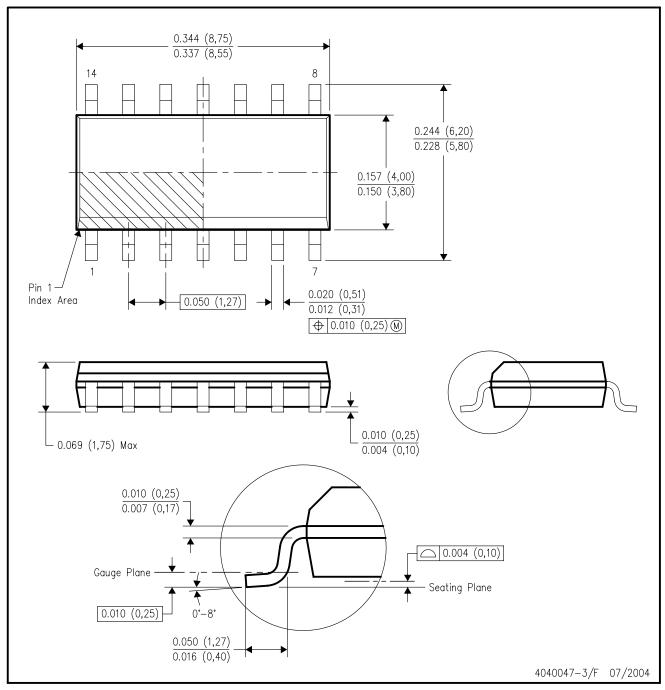
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

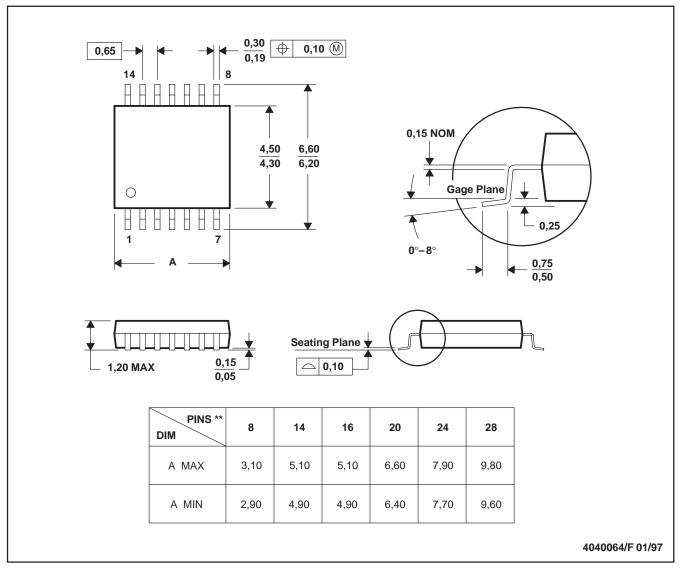
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265